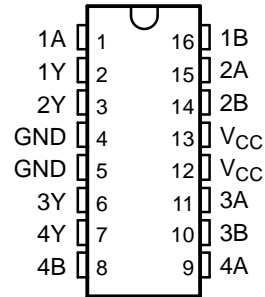


FEATURES

- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typ Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic 300-mil DIPs (N)

D OR N PACKAGE (TOP VIEW)



DESCRIPTION

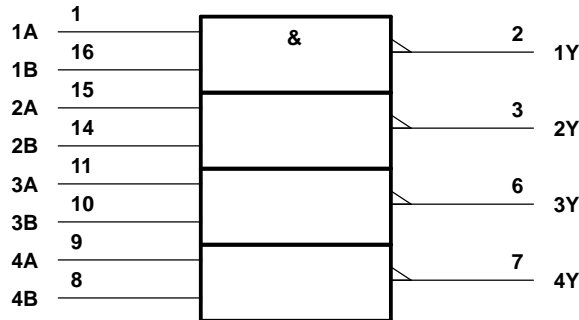
This device contains four independent 2-input NAND gates. It performs the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The 74AC11000 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (EACH GATE)

INPUTS		OUTPUT Y
A	B	Y
H	H	L
L	X	H
X	L	H

LOGIC SYMBOL⁽¹⁾



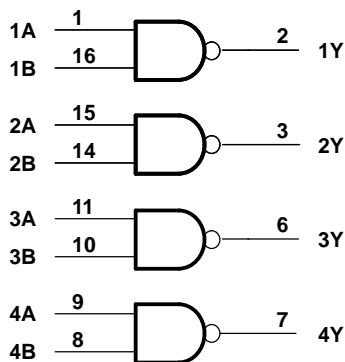
(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I	Input voltage range ⁽²⁾	-0.5	$V_{CC} + 0.5$	V
V_O	Output voltage range ⁽²⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$ or $V_I > V_{CC}$		±20 mA
I_{OK}	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$		±50 mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		±50 mA
	Continuous current through V_{CC} or GND			±100 mA
	Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) ⁽³⁾	D package		1.3 W
		N package		1.1 W
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	3	5	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 3\text{ V}$	2.1		V
		$V_{CC} = 4.5\text{ V}$	3.15		
		$V_{CC} = 5.5\text{ V}$	3.85		
V_{IL}	Low-level input voltage	$V_{CC} = 3\text{ V}$		0.9	V
		$V_{CC} = 4.5\text{ V}$		1.35	
		$V_{CC} = 5.5\text{ V}$		1.65	
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 3\text{ V}$		–4	mA
		$V_{CC} = 4.5\text{ V}$		–24	
		$V_{CC} = 5.5\text{ V}$		–24	
I_{OL}	Low-level output current	$V_{CC} = 3\text{ V}$		12	mA
		$V_{CC} = 4.5\text{ V}$		24	
		$V_{CC} = 5.5\text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise fall rate	0		10	ns/V
T_A	Operating free-air temperature	–40		85	°C

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	$I_{OH} = -50\ \mu\text{A}$	3 V	2.9		2.9	V		
		4.5 V	4.4		4.4			
		5.5 V	5.4		5.4			
	$I_{OH} = -4\ \text{mA}$	3 V	2.58		2.48			
		4.5 V	3.94		3.8			
		5.5 V	4.94		4.8			
$I_{OH} = -24\ \text{mA}$	5.5 V			3.85				
V_{OL}	$I_{OL} = 50\ \mu\text{A}$	3 V		0.1	0.1	V		
		4.5 V		0.1	0.1			
		5.5 V		0.1	0.1			
	$I_{OL} = 12\ \text{mA}$	3 V		0.36	0.44			
		4.5 V		0.36	0.44			
		5.5 V		0.36	0.44			
$I_{OL} = 24\ \text{mA}$	5.5 V			1.65				
I_I	$V_I = V_{CC}$ or GND	5.5 V		± 0.1	± 1	μA		
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		4	40	μA		
C_i	$V_I = V_{CC}$ or GND	5 V		3.5		pF		

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

74AC11000 QUADRUPLE 2-INPUT POSITIVE-NAND GATE

SCLS054B–APRIL 1987–REVISED JUNE 2005

Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	7.2	9.8	1.5	11.1	ns
t_{PHL}			1.5	5.8	8.6	1.5	9.6	

Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 1)

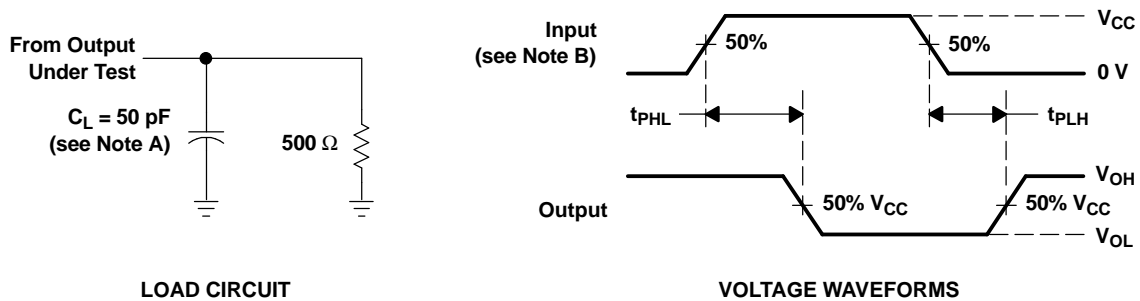
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	5	6.5	1.5	7.4	ns
t_{PHL}			1.5	4.4	6.1	1.5	6.8	

Operating Characteristics

$V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per gate	$C_L = 50 \text{ pF}$, $f = 1 \text{ MHz}$	33	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC11000D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11000NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11000NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11000NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC11000DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
74AC11000NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC11000DR	SOIC	D	16	2500	333.2	345.9	28.6
74AC11000NSR	SO	NS	16	2000	367.0	367.0	38.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211283-4/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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